DATA SHEET

74ALVCH162827

20-bit buffer/line driver, non-inverting, with 30Ω termination resistors (3-State)

Product specification

1998 Sep 29

IC24 Data Handbook

Philips Semiconductors

PHILIPS

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FEATURES

- Complies with JEDEC standard no. 8-1A.
- CMOS low power consumption
- Direct interface with TTL levels
- Current drive ± 12 mA at 3.0 V
- MULTIBYTE™ flow-through standard pin-out architecture
- Low inductance multiple V_{CC} and GND pins for minimum noise and ground bounce
- Integrated 30 Ω termination resistors

DESCRIPTION

The 74ALVCH162827 high-performance CMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ALVCH162827 20-bit buffers provide high performance bus interface buffering for wide data/address paths or buses carrying parity. They have NAND Output Enables ($n\overline{OE}1$, $n\overline{OE}2$) for maximum control flexibility.

The 74ALVCH162827 is designed with 30Ω series resistance in both the pull-up and pull-down output structures. This design reduces line noise in applications such as memory address drivers, clock drivers and bus receivers/transmitters.

To ensure the high impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking/current-sourcing capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

QUICK REFERENCE DATA

GND = 0V; T_{amb} = 25°C; $t_r = t_f$ = 2.5ns

SYMBOL	PARAMETER	CONDITIONS		TYPICAL	UNIT
t_{PHL}/t_{PLH}	Propagation delay nAn to nYn	V_{CC} = 2.5V, C_L = 30pF V_{CC} = 3.3V, C_L = 50pF		2.9 2.9	ns
C_I	Input capacitance			5	pF
C_{PD}	Power dissipation capacitance per latch	V_I = GND to V_{CC}[1]	Output enabled	14	pF
			Output disabled	3	

NOTES:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW):
   $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where:
   f_i = input frequency in MHz; C_L = output load capacity in pF;
   f_o = output frequency in MHz; V_{CC} = supply voltage in V;
   $\Sigma (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
56-Pin Plastic TSSOP Type II	–40°C to +85°C	74ALVCH162827DGG	ACH162827DGG	SOT364-1

PIN DESCRIPTION

PIN NUMBER	SYMBOL	FUNCTION
55, 54, 52, 51, 49, 48, 47, 45, 44, 43, 42, 41, 40, 38, 37, 36, 34, 33, 31, 30	1A0 - 1A9 2A0 - 2A9	Data inputs
2, 3, 5, 6, 8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21, 23, 24, 26, 27	1Y0 - 1Y9 2Y0 - 2Y9	Data outputs
1, 56, 28, 29	$1\overline{OE}1$ $1\overline{OE}2$, $2\overline{OE}1$, $2\overline{OE}2$	Output enable inputs (active-LOW)
4, 11, 18, 25, 32, 39, 46, 53	GND	Ground (0V)
7, 22, 35, 50	V_{CC}	Positive supply voltage

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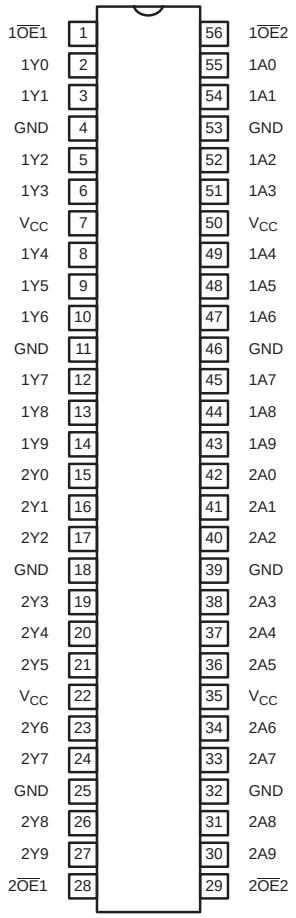
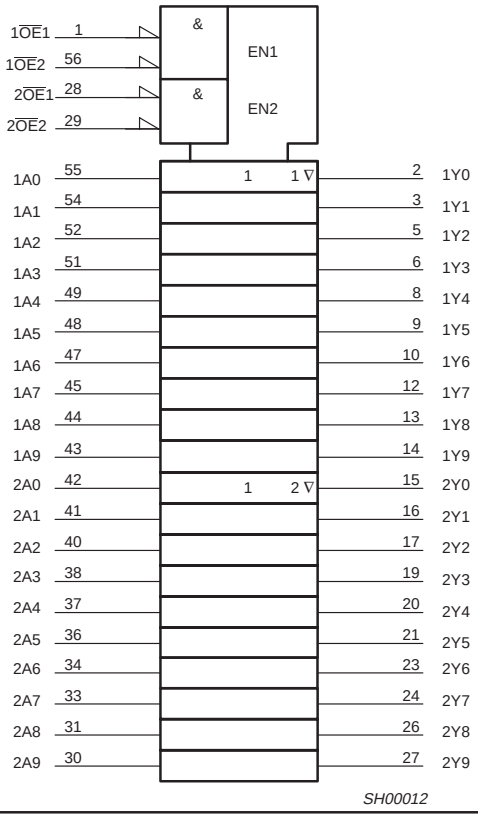
PIN CONFIGURATION



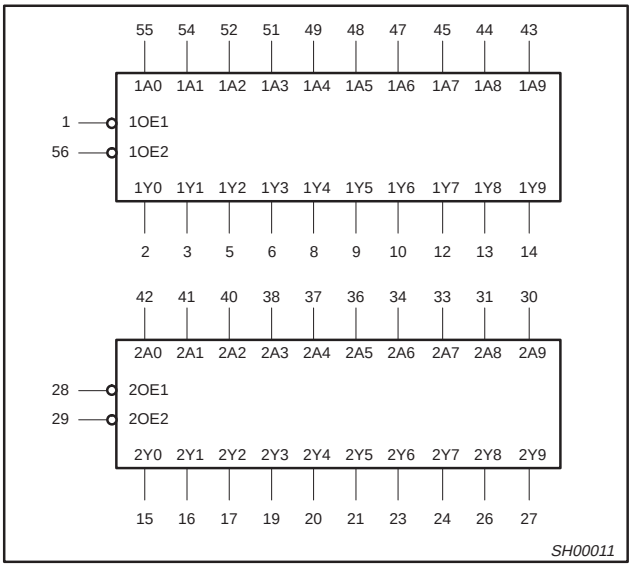
SH00010

LOGIC SYMBOL (IEEE/IEC)



SH00012

LOGIC SYMBOL



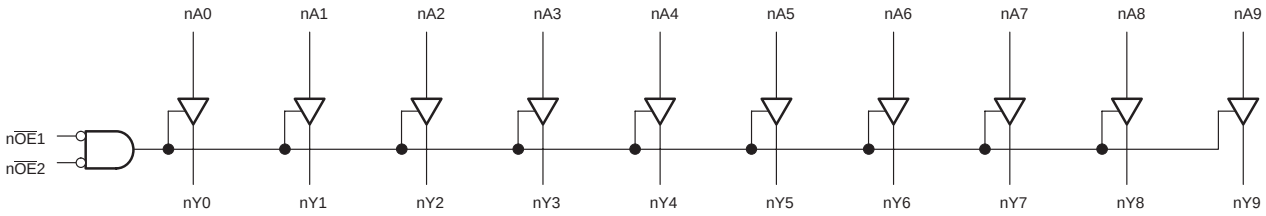
SH00011

FUNCTION TABLE

INPUTS			OUTPUT	OPERATING MODE
$n\overline{OE}1$	$n\overline{OE}2$	nAn	nYn	
L	L	L	L	Transparent
L	L	H	H	Transparent
H	X	X	Z	High impedance
X	H	X	Z	High impedance

X = Don't care
Z = High impedance "off" state
H = High voltage level
L = Low voltage level

LOGIC DIAGRAM



RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V_{CC}	DC supply voltage 2.5V range (for max. speed performance @ 30 pF output load)		2.3	2.7	V
	DC supply voltage 3.3V range (for max. speed performance @ 50 pF output load)		3.0	3.6	
V_I	DC Input voltage range		0	V_{CC}	V
V_O	DC output voltage range		0	V_{CC}	V
T_{amb}	Operating free-air temperature range		–40	+85	°C
t_r, t_f	Input rise and fall times	V_{CC} = 2.3 to 3.0V V_{CC} = 3.0 to 3.6V	0 0	20 10	ns/V

ABSOLUTE MAXIMUM RATINGS

In accordance with the Absolute Maximum Rating System (IEC 134)
Voltages are referenced to GND (ground = 0V)

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		–0.5 to +4.6	V
I_{IK}	DC input diode current	$V_I < 0$	–50	mA
V_I	DC input voltage	Note 1	–0.5 to +4.6	V
I_{OK}	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	±50	mA
V_O	DC output voltage	Note 1	–0.5 to V_{CC} +0.5	V
I_O	DC output source or sink current	V_O = 0 to V_{CC}	±50	mA
I_{GND}, I_{CC}	DC V_{CC} or GND current		±100	mA
T_{stg}	Storage temperature range		–65 to +150	°C
P_{TOT}	Power dissipation per package –plastic thin-medium-shrink (TSSOP)	For temperature range: –40 to +125 °C above +55°C derate linearly with 8 mW/K	600	mW

NOTE:
1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltage are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			Temp = -40°C to +85°C			
			MIN	TYP[1]	MAX	
V_{IH}	HIGH level Input voltage	V_{CC} = 2.3 to 2.7V	1.7	1.2		V
		V_{CC} = 2.7 to 3.6V	2.0	1.5		
V_{IL}	LOW level Input voltage	V_{CC} = 2.3 to 2.7V		1.2	0.7	V
		V_{CC} = 2.7 to 3.6V		1.5	0.8	
V_{OH}	HIGH level output voltage	V_{CC} = 2.3 to 3.6V; $V_I = V_{IH}$ or V_{IL}; I_O = –100µA	V_{CC} – 0.2	V_{CC}		V
		V_{CC} = 2.3V; $V_I = V_{IH}$ or V_{IL}; I_O = –4mA	V_{CC} – 0.4	V_{CC} – 0.11		
		V_{CC} = 2.3V; $V_I = V_{IH}$ or V_{IL}; I_O = –6mA	V_{CC} – 0.6	V_{CC} – 0.17		
		V_{CC} = 2.7V; $V_I = V_{IH}$ or V_{IL}; I_O = –4mA	V_{CC} – 0.5	V_{CC} – 0.09		
		V_{CC} = 2.7V; $V_I = V_{IH}$ or V_{IL}; I_O = –8mA	V_{CC} – 0.7	V_{CC} – 0.19		
		V_{CC} = 3.0V; $V_I = V_{IH}$ or V_{IL}; I_O = –6mA	V_{CC} – 0.6	V_{CC} – 0.13		
		V_{CC} = 3.0V; $V_I = V_{IH}$ or V_{IL}; I_O = –12mA	V_{CC} – 1.0	V_{CC} – 0.27		
V_{OL}	LOW level output voltage	V_{CC} = 2.3 to 3.6V; $V_I = V_{IH}$ or V_{IL}; I_O = 100µA		GND	0.20	V
		V_{CC} = 2.3V; $V_I = V_{IH}$ or V_{IL}; I_O = 4mA		0.07	0.40	
		V_{CC} = 2.3V; $V_I = V_{IH}$ or V_{IL}; I_O = 6mA		0.11	0.55	
		V_{CC} = 2.7V; $V_I = V_{IH}$ or V_{IL}; I_O = 4mA		0.06	0.40	
		V_{CC} = 2.7V; $V_I = V_{IH}$ or V_{IL}; I_O = 8mA		0.13	0.60	
		V_{CC} = 3.0V; $V_I = V_{IH}$ or V_{IL}; I_O = 6mA		0.09	0.55	
		V_{CC} = 3.0V; $V_I = V_{IH}$ or V_{IL}; I_O = 12mA		0.19	0.80	
I_I	Input leakage current	V_{CC} = 2.3 to 3.6V; $V_I = V_{CC}$ or GND		0.1	5	µA
I_{OZ}	3-State output OFF-state current	V_{CC} = 2.3 to 3.6V; $V_I = V_{IH}$ or V_{IL}; $V_O = V_{CC}$ or GND		0.1	10	µA
I_{CC}	Quiescent supply current	V_{CC} = 2.3 to 3.6V; $V_I = V_{CC}$ or GND; I_O = 0		0.2	40	µA
ΔI_{CC}	Additional quiescent supply current	V_{CC} = 2.3V to 3.6V; $V_I = V_{CC}$ – 0.6V; I_O = 0		150	750	µA
I_{BHL}	Bus hold LOW sustaining current	V_{CC} = 2.3V; V_I = 0.7V[2]	45	–		µA
I_{BHH}	Bus hold HIGH sustaining current	V_{CC} = 2.3V; V_I = 1.7V[2]	–45			µA
		V_{CC} = 3.0V; V_I = 2.0V[2]	–75	–175		
I_{BHLO}	Bus hold LOW overdrive current	V_{CC} = 3.6V[2]	500			µA
I_{BHHO}	Bus hold HIGH overdrive current	V_{CC} = 3.6V[2]	–500			µA

NOTES:

1. All typical values are at T_{amb} = 25°C.
2. Valid for data inputs of bus hold parts.

AC CHARACTERISTICS FOR V_{CC} = 2.5V ± 0.2V

GND = 0V; $t_r = t_f \leq 2.0$ns; C_L = 30pF

SYMBOL	PARAMETER	WAVEFORM	LIMITS			UNIT
			V_{CC} = 2.5 ± 0.2V			
			MIN	TYP[1]	MAX	
t_{PHL}/t_{PLH}	Propagation delay nAn to nYn	1, 3	1.0	2.9	4.6	ns
t_{PZH}/t_{PZL}	3-State output enable time $n\overline{OE}$n to nYn	2, 3	1.4	3.9	6.4	ns
t_{PHZ}/t_{PLZ}	3-State output disable time $n\overline{OE}$n to nYn	2,3	1.7	2.2	5.9	ns

NOTE:
1. All typical values are at V_{CC} = 2.5V and T_{amb} = 25°C.

AC CHARACTERISTICS FOR V_{CC} = 3.0V ± 0.3V

GND = 0V; $t_r = t_f \leq 2.5$ns; C_L = 50pF

SYMBOL	PARAMETER	WAVEFORM	LIMITS			LIMITS		UNIT
			V_{CC} = 3.3 ± 0.3V			V_{CC} = 2.7V		
			MIN	TYP[1, 2]	MAX	TYP[1]	MAX	
t_{PHL}/t_{PLH}	Propagation delay nAn to nYn	1, 3	1.5	2.9	4.2	3.1	4.7	ns
t_{PZH}/t_{PZL}	3-State output enable time $n\overline{OE}$n to nYn	2, 3	1.6	3.7	5.4	4.4	6.5	ns
t_{PHZ}/t_{PLZ}	3-State output disable time $n\overline{OE}$n to nYn	2, 3	1.8	3.0	4.7	3.2	5.2	ns

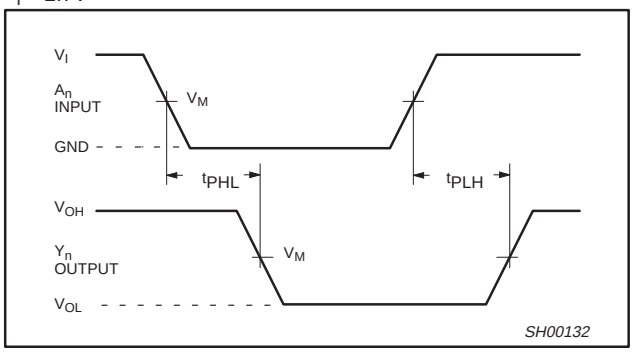
NOTES:
1. All typical values are at V_{CC} T_{amb} = 25°C.
2. Typical value is measured at V_{CC} = 3.3V.

AC WAVEFORMS FOR V_{CC} = 2.3V TO 2.7V

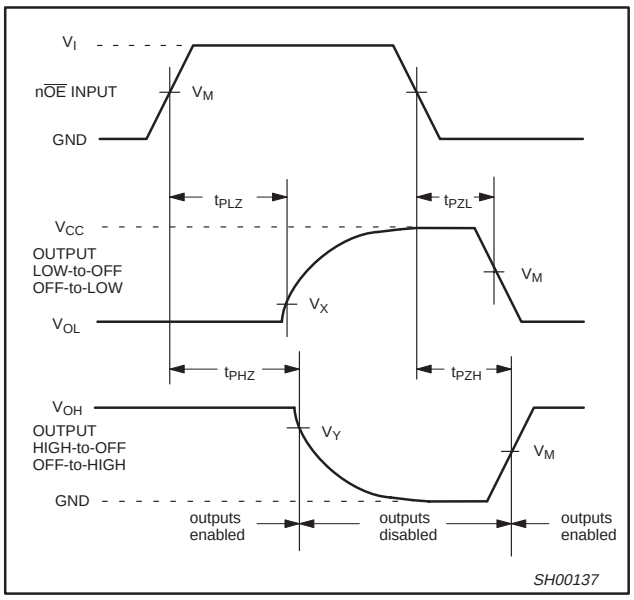
$V_M = 0.5\ V_{CC}$
$V_X = V_{OL} + 0.15V$
$V_Y = V_{OH} – 0.15V$
V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.
$V_I = V_{CC}$

AC WAVEFORMS FOR V_{CC} = 3.0V TO 3.6V AND V_{CC} = 2.7V RANGE

$V_M = 1.5\ V$
$V_X = V_{OL} + 0.3V$
$V_Y = V_{OH} – 0.3V$
V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.
$V_I = 2.7V$

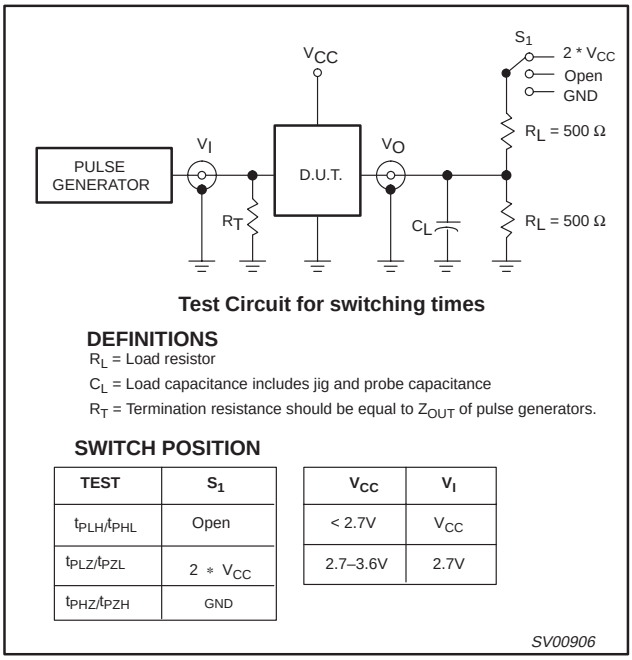


Waveform 1. Input (nAx) to Output (nYx) Propagation Delays



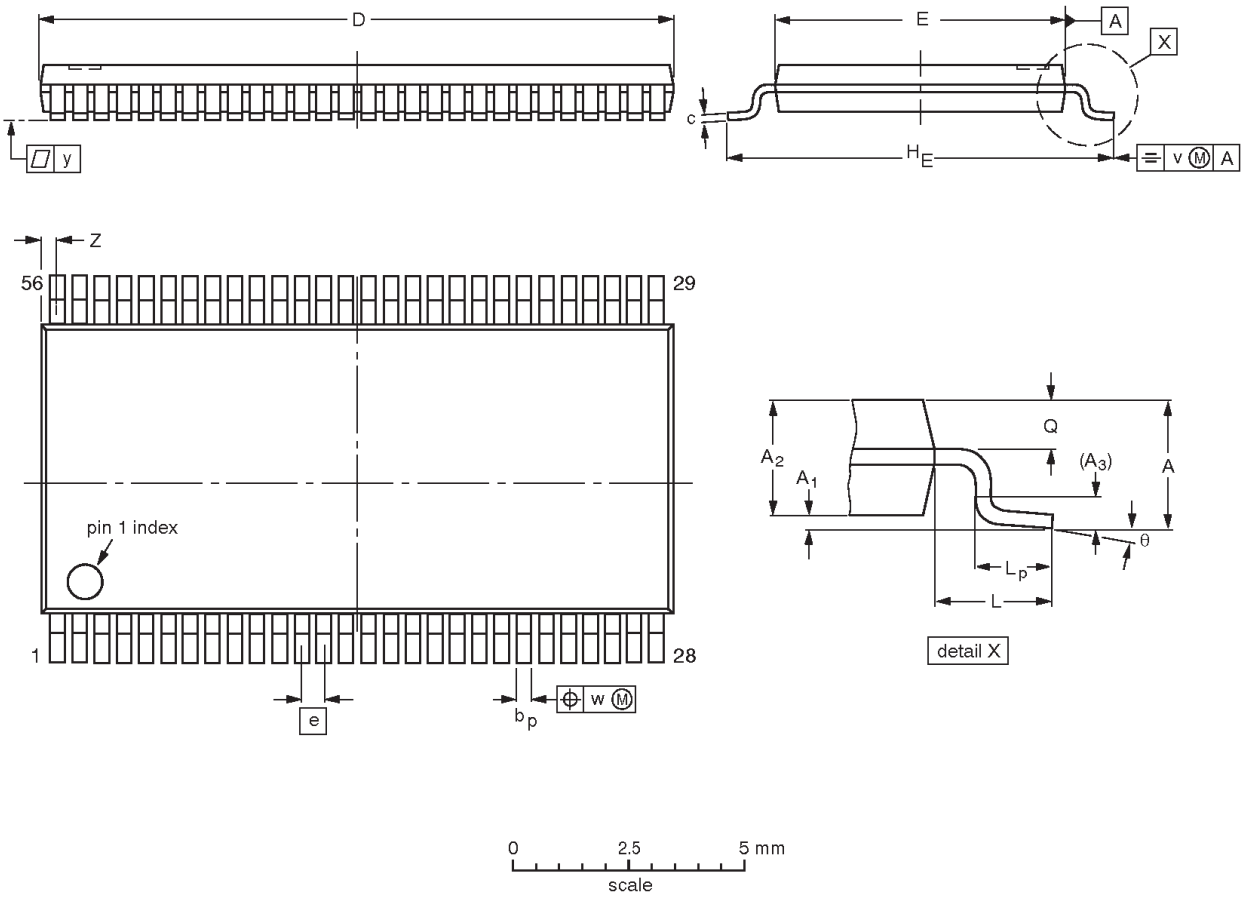
Waveform 2. 3-State Output Enable and Disable Times

TEST CIRCUIT AND WAVEFORM



Waveform 3. Load circuitry for switching times

TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1mm **SOT364-1**



DIMENSIONS (mm are the original dimensions).

UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	14.1 13.9	6.2 6.0	0.5	8.3 7.9	1.0	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.5 0.1	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES					EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ				
SOT364-1		MO-153EE					~~93-02-03~~ 95-02-10

NOTES

DEFINITIONS

Data Sheet Identification	Product Status	Definition
Objective Specification	Formative or in Design	This data sheet contains the design target or goal specifications for product development. Specifications may change in any manner without notice.
Preliminary Specification	Preproduction Product	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make changes at any time without notice in order to improve design and supply the best possible product.
Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.

Philips Semiconductors
811 East Arques Avenue
P.O. Box 3409
Sunnyvale, California 94088–3409
Telephone 800-234-7381

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